



## Material Content Data Sheet



<b>Sales Product Name</b>		IPL60R299CP		<b>Issued</b>		19. July 2018			
<b>MA#</b>		MA000842340							
<b>Package</b>		PG-VSON-4-1		<b>Weight*</b>		187.72 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	6.215	3.31	3.31	33107	33107	
leadframe	inorganic material	phosphorus	7723-14-0	0.020	0.01		108		
	non noble metal	zinc	7440-66-6	0.081	0.04		431		
	non noble metal	iron	7439-89-6	1.619	0.86		8622		
wire	non noble metal	copper	7440-50-8	65.718	35.01	35.92	350093	359254	
	non noble metal	copper	7440-50-8	0.729	0.39	0.39	3883	3883	
	encapsulation	organic material	carbon black	1333-86-4	0.215	0.11		1146	
plastics	plastics	epoxy resin	-	11.084	5.90		59046		
	inorganic material	silicondioxide	60676-86-0	96.312	51.33	57.34	513075	573266	
leadfinish	non noble metal	tin	7440-31-5	2.397	1.28	1.28	12772	12772	
plating	noble metal	silver	7440-22-4	0.252	0.13	0.13	1342	1343	
solder	non noble metal	tin	7440-31-5	0.061	0.03		328		
	noble metal	silver	7440-22-4	0.077	0.04		409		
	non noble metal	lead	7439-92-1	2.935	1.56	1.63	15638	16375	
*deviation	< 10%				Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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